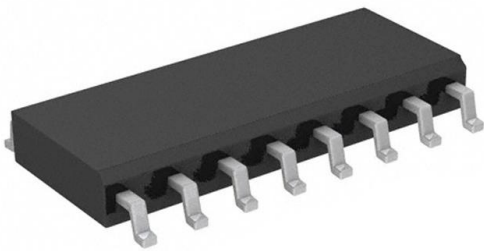


IL 261-3 Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	IL 261-3-DG
Manufacturer	NVE Corp/Isolation Products
Manufacturer Product Number	IL 261-3
Description	DGTL ISO 2500VRMS 5CH GP 16SOIC
Detailed Description	General Purpose Digital Isolator 2500Vrms 5 Channel 110Mbps 30kV/ μ s CMTI 16-SOIC (0.154", 3.90mm Width)

This model IL 261-3 is available at DiGi Electronics.

DiGi Electronics offers a global database of semiconductor and electronic component datasheets.

We welcome your inquiries regarding pricing, lead time, or other product-related questions.

 [Request a Quote](#)

 [Datasheet Search](#)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

IL 261-3

Series:

IsoLoop®, IL261

Technology:

GMR (Giant Magnetoresistive)

Isolated Power:

No

Inputs - Side 1/Side 2:

4/1

Voltage - Isolation:

2500Vrms

Data Rate:

110Mbps

Pulse Width Distortion (Max):

3ns

Voltage - Supply:

3V ~ 5.5V

Mounting Type:

Surface Mount

Supplier Device Package:

16-SOIC

Manufacturer:

NVE Corp/Isolation Products

Product Status:

Active

Type:

General Purpose

Number of Channels:

5

Channel Type:

Unidirectional

Common Mode Transient Immunity (Min):

30kV/μs

Propagation Delay tpLH / tpHL (Max):

15ns, 15ns

Rise / Fall Time (Typ):

1ns, 1ns

Operating Temperature:

-40°C ~ 85°C

Package / Case:

16-SOIC (0.154", 3.90mm Width)

Base Product Number:

IL 261

Environmental & Export classification

RoHS Status:

RoHS non-compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

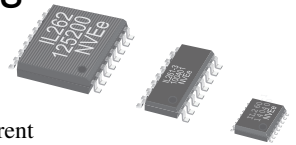
Moisture Sensitivity Level (MSL):

1 (Unlimited)

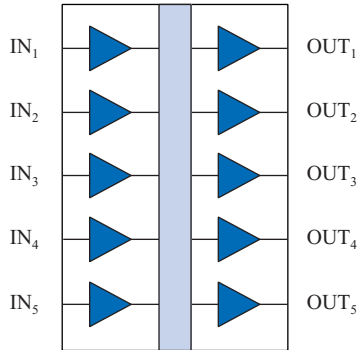
ECCN:

5A991A

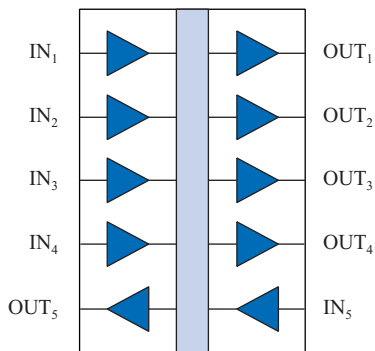
High Speed Five-Channel Digital Isolators



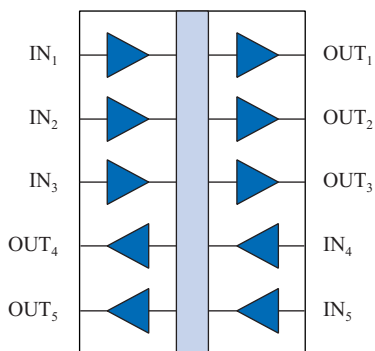
Functional Diagrams



IL260



IL261



IL262

Features

- High Speed: 110 Mbps
- 1.2 mA/channel typical quiescent current
- Very high isolation: 6 kV_{RMS} Reinforced Isolation (VE-Series)
- 50 kV/μs typ.; 30 kV/μs min. common mode transient immunity
- No carrier or clock for low EMI emissions and susceptibility
- -40 to 85 °C operating temperature
- 44000-year barrier life
- Excellent magnetic immunity
- 2 ns typical pulse width distortion
- 100 ps pulse jitter
- 4 ns typical propagation delay skew
- 10 ns typical propagation delay
- 2 ns channel-to-channel skew
- IEC 60747-17 (VDE 0884-17):2021-10 certified; UL 1577 recognized
- 0.15" and True 8™ mm 16-pin SOIC; 16-pin QSOP packages

Applications

- ADCs and DACs
- Multiplexed data transmission
- Board-to-board communication
- Peripheral interfaces
- Equipment covered under IEC 61010-1 Edition 3
- >5 kV_{RMS} rated IEC 60601-1 medical applications

Description

NVE's IL260-Series five-channel high-speed digital isolators are CMOS devices manufactured with NVE's patented* spintronic Giant Magnetoresistive (GMR) technology.

A unique ceramic/polymer composite barrier provides excellent isolation and virtually unlimited barrier life.

Performance is specified over the temperature range of -40 °C to +85 °C without derating. All transmit and receive channels operate at 110 Mbps over the full temperature and supply voltage range. The symmetric magnetic coupling barrier provides a typical propagation delay of only 10 ns and a pulse width distortion of 2 ns, achieving the best specifications of any isolator. The fifth channel can be used to distribute isolated clocks or handshake signals to multiple delta-sigma A/D converters.

Parts are available in ultraminiature 16-pin QSOPs, as well as 0.15" and 0.3"-wide SOIC packages. V-Series versions offer extremely high isolation voltage of 6 kV_{RMS}, and true 8 mm creepage.

High channel density and low jitter, skew, and pulse-width distortion makes these devices ideal for isolating ADCs and DACs, parallel buses and peripheral interfaces.



IL260/IL261/IL262

Absolute Maximum Ratings⁽¹⁾

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Storage Temperature	T_S	-55		150	°C	
Junction Temperature	T_J	-55		150	°C	
Supply Voltage	V_{DD1}, V_{DD2}	-0.5		7	V	
Input Voltage	V_I	-0.5		$V_{DD} + 0.5$	V	
Output Voltage	V_O	-0.5		$V_{DD} + 0.5$	V	
Output Current Drive	I_O	-10		10	mA	
Lead Solder Temperature				260	°C	10 sec.
ESD			2		kV	HBM

Recommended Operating Conditions

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Ambient Operating Temperature	T_A	-40		85	°C	
Junction Temperature	T_J	-40		100	°C	
Supply Voltage	V_{DD1}, V_{DD2}	2.7		5.5	V	
Logic High Input Voltage	V_{IH}	2.4		V_{DD}	V	
Logic Low Input Voltage	V_{IL}	0		0.8	V	
Input Signal Rise and Fall Times	t_{IR}, t_{IF}			1	μs	



IL260/IL261/IL262

Safety and Approvals

IEC 60747-17 (VDE 0884-17):2021-10:

“VE” version (Reinforced Isolation; VDE File Number 5016933-4880-0002)

- Working Voltage (V_{IORM}): 1200 V_{RMS} (1700 V_{PK}) with 20% Safety Factor; pollution degree 2
- Isolation voltage (V_{ISO}): 6000 V_{RMS}
- Surge immunity (V_{IOSM}): 12.8 kV $_{PK}$
- Surge rating: 8000 V
- Transient overvoltage (V_{IOTM}): 6000 V_{PK}
- Each part tested at 2387 V_{PK} for 1 second, 5 pC partial discharge limit
- Samples tested at 6000 V_{PK} for 60 sec.; then 2122 V_{PK} for 10 sec. with 5 pC partial discharge limit

Standard versions (Basic Isolation; VDE File Number 5016933-4880-0001)

- Isolation voltage (V_{ISO}): 2500 V_{RMS}
- Transient overvoltage (V_{IOTM}): 4000 V_{PK}
- Surge rating: 4000 V
- Each part tested at 1590 V_{PK} for 1 second, 5 pC partial discharge limit.
- Samples tested at 4000 V_{PK} for 60 sec.; then 1358 V_{PK} for 10 sec. with 5 pC partial discharge limit.
- Working Voltage (V_{IORM} ; pollution degree 2):

Package	Part No. Suffix	Working Voltage
QSOP16	-1	600 V_{RMS}
Narrow-body SOIC16	-3	700 V_{RMS}
Wide-body SOIC16/True 8™	None	600 V_{RMS}

Safety-Limiting Values	Symbol	Value	Units
Safety rating ambient temperature	T_S	180	°C
Safety rating power (180 °C)	P_S	270	mW
Supply current safety rating (total of supplies)	I_S	54	mA

UL 1577 (Component Recognition Program File Number E207481)

V-Series isolation grade

6 kV rating; tested at 7.2 kV $_{RMS}$ (10.2 kV $_{PK}$) for 1 second; each lot sample tested at 6 kV $_{RMS}$ (8485 V $_{PK}$) for 1 minute.

Standard isolation grade

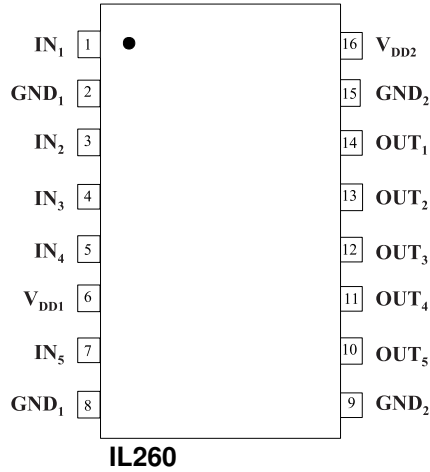
Each part tested at 3000 V_{RMS} (4243 V $_{PK}$) for 1 second; each lot sample tested at 2500 V_{RMS} (3536 V $_{PK}$) for 1 minute.

Soldering Profile

Per JEDEC J-STD-020C, MSL 1

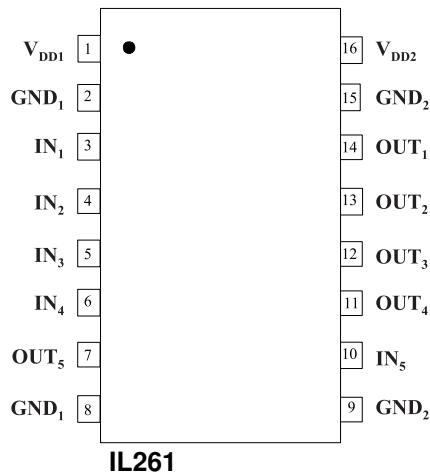
IL260 Pin Connections

1	IN ₁	Input 1
2	GND ₁	Ground*
3	IN ₂	Input 2
4	IN ₃	Input 3
5	IN ₄	Input 4
6	V _{DD1}	Supply Voltage 1
7	IN ₅	Input 5
8	GND ₁	Ground*
9	GND ₂	Ground*
10	OUT ₅	Output 5
11	OUT ₄	Output 4
12	OUT ₃	Output 3
13	OUT ₂	Output 2
14	OUT ₁	Output 1
15	GND ₂	Ground*
16	V _{DD2}	Supply Voltage 2



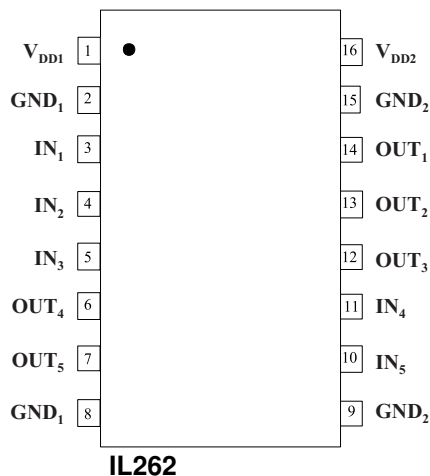
IL261 Pin Connections

1	V _{DD1}	Supply Voltage 1
2	GND ₁	Ground*
3	IN ₁	Input 1
4	IN ₂	Input 2
5	IN ₃	Input 3
6	IN ₄	Input 4
7	OUT ₅	Output 5
8	GND ₁	Ground*
9	GND ₂	Ground*
10	IN ₅	Input 5
11	OUT ₄	Output 4
12	OUT ₃	Output 3
13	OUT ₂	Output 2
14	OUT ₁	Output 1
15	GND ₂	Ground*
16	V _{DD2}	Supply Voltage 2



IL262 Pin Connections

1	V _{DD1}	Supply Voltage 1
2	GND ₁	Ground*
3	IN ₁	Input 1
4	IN ₂	Input 2
5	IN ₃	Input 3
6	OUT ₄	Output 4
7	OUT ₅	Output 5
8	GND ₁	Ground*
9	GND ₂	Ground*
10	IN ₅	Input 5
11	IN ₄	Input 4
12	OUT ₃	Output 3
13	OUT ₂	Output 2
14	OUT ₁	Output 1
15	GND ₂	Ground*
16	V _{DD2}	Supply Voltage 2



*NOTE: Pins 2 and 8 are internally connected, as are pins 9 and 15.



IL260/IL261/IL262

3.3 Volt Electrical Specifications (T _{min} to T _{max})							
Parameters		Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Quiescent Current	IL260	I _{DD1}		300	400	μA	
	IL261			1.2	1.75	mA	
	IL262			2.4	3.5	mA	
Output Quiescent Current	IL260	I _{DD2}		6	8.75	mA	
	IL261			4.8	7	mA	
	IL262			3.6	5.25	mA	
Logic Input Current		I _I	-10		10	μA	
Logic High Output Voltage		V _{OH}		V _{DD} -0.1	V _{DD}	V	I _O = -20 μA, V _I =V _{IH}
				0.8 x V _{DD}	0.9 x V _{DD}		I _O = -4 mA, V _I =V _{IH}
Logic Low Output Voltage		V _{OL}		0	0.1	V	I _O = 20 μA, V _I =V _{IL}
				0.5	0.8		I _O = 4 mA, V _I =V _{IL}

Switching Specifications (2.7 V < V _{DD} < 3.6 V)							
Maximum Data Rate			100	110		Mbps	C _L = 15 pF
Minimum Pulse Width ⁽⁷⁾		PW	10			ns	50% Points, V _O
Propagation Delay Input to Output (High to Low)		t _{PHL}		12	18	ns	C _L = 15 pF
Propagation Delay Input to Output (Low to High)		t _{PLH}		12	18	ns	C _L = 15 pF
Pulse Width Distortion t _{PHL} -t _{PLH} ⁽²⁾		PWD		2	3	ns	C _L = 15 pF
Propagation Delay Skew ⁽³⁾		t _{PSK}		4	6	ns	C _L = 15 pF
Output Rise Time (10%-90%)		t _R		2	4	ns	C _L = 15 pF
Output Fall Time (10%-90%)		t _F		2	4	ns	C _L = 15 pF
Common Mode Transient Immunity (Output Logic High to Logic Low) ⁽⁴⁾		CM _H , CM _L	30	50		kV/μs	V _{CM} = 1500 V _{DC} t _{TRANSIENT} = 25 ns
Channel-to-Channel Skew				2	3	ns	C _L = 15 pF
Dynamic Power Consumption ⁽⁶⁾				140	240	μA/Mbps	per channel

Magnetic Field Immunity ⁽⁸⁾ (V _{DD2} = 3 V, 3 V < V _{DD1} < 5.5 V)							
Power Frequency Magnetic Immunity		H _{PF}		1500		A/m	50Hz/60Hz
Pulse Magnetic Field Immunity		H _{PM}		2000		A/m	t _p = 8μs
Damped Oscillatory Magnetic Field		H _{OSC}		2000		A/m	0.1Hz - 1MHz
Cross-axis Immunity Multiplier ⁽⁹⁾		K _X		2.5			



IL260/IL261/IL262

5 Volt Electrical Specifications (T _{min} to T _{max})							
Parameters		Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Quiescent Current	IL260	I _{DD1}		350	500	μA	
	IL261			1.8	2.5	mA	
	IL262			3.6	5	mA	
Output Quiescent Current	IL260	I _{DD2}		9	12.5	mA	
	IL261			7.2	10	mA	
	IL262			5.4	7.5	mA	
Logic Input Current		I _i	-10		10	μA	
Logic High Output Voltage		V _{OH}	V _{DD} -0.1	V _{DD}		V	I _O = -20 μA, V _i = V _{IH}
			0.8 x V _{DD}	0.9 x V _{DD}			I _O = -4 mA, V _i = V _{IH}
Logic Low Output Voltage		V _{OL}		0	0.1	V	I _O = 20 μA, V _i = V _{IL}
				0.5	0.8		I _O = 4 mA, V _i = V _{IL}

Switching Specifications (V _{DD} = 5 V)							
Maximum Data Rate			100	110		Mbps	C _L = 15 pF
Minimum Pulse Width ⁽⁷⁾		PW	10			ns	50% Points, V _O
Propagation Delay Input to Output (High to Low)		t _{PHL}		10	15	ns	C _L = 15 pF
Propagation Delay Input to Output (Low to High)		t _{PLH}		10	15	ns	C _L = 15 pF
Pulse Width Distortion t _{PHL} - t _{PLH} ⁽²⁾		PWD		2	3	ns	C _L = 15 pF
Pulse Jitter ⁽¹⁰⁾		t _J		100		ps	C _L = 15 pF
Propagation Delay Skew ⁽³⁾		t _{PSK}		4	6	ns	C _L = 15 pF
Output Rise Time (10%-90%)		t _R		1	3	ns	C _L = 15 pF
Output Fall Time (10%-90%)		t _F		1	3	ns	C _L = 15 pF
Common Mode Transient Immunity (Output Logic High to Logic Low) ⁽⁴⁾		CM _H , CM _L	30	50		kV/μs	V _{CM} = 1500 V _{DC} t _{TRANSIENT} = 25 ns
Channel-to-Channel Skew				2	3	ns	C _L = 15 pF
Dynamic Power Consumption ⁽⁶⁾				200	340	μA/Mbps	per channel

Magnetic Field Immunity ⁽⁸⁾ (V _{DD2} = 5 V, 3 V < V _{DD1} < 5.5V)							
Power Frequency Magnetic Immunity		H _{PF}		3500		A/m	50Hz/60Hz
Pulse Magnetic Field Immunity		H _{PM}		4500		A/m	t _p = 8μs
Damped Oscillatory Magnetic Field		H _{OSC}		4500		A/m	0.1Hz - 1MHz
Cross-axis Immunity Multiplier ⁽⁹⁾		K _X		2.5			



IL260/IL261/IL262

Insulation Specifications							
Parameter		Symbol	Min.	Typ.	Max.	Units	Test Conditions
Creepage Distance (external)	QSOP		4.03			mm	Per IEC 60601
	0.15" SOIC		4.03				
	0.3" SOIC		8.03	8.3			
Total Barrier Thickness (internal)			0.012	0.016		mm	
Leakage Current ⁽⁵⁾				0.2		μA_{RMS}	240 V_{RMS}
Barrier Resistance ⁽⁵⁾		R_{IO}		$>10^{14}$		Ω	500 V
Barrier Capacitance ⁽⁵⁾		C_{IO}		5		pF	f = 1 MHz
Comparative Tracking Index		CTI	≥ 600			V_{RMS}	Per IEC 60112
High Voltage Endurance (Maximum Barrier Voltage for Indefinite Life)	AC	V_{IO}	1000			V_{RMS}	At maximum operating temperature
	DC		1500			V_{DC}	
Surge Immunity ("V" Versions)		V_{IOSM}	12.8			kV _{PK}	Per IEC 61000-4-5
Barrier Life				44000		Years	100°C, 1000 V_{RMS} , 60% CL activation energy

Thermal Characteristics									
Parameter		Symbol	Min.	Typ.	Max.	Units	Test Conditions		
Junction–Ambient Thermal Resistance	QSOP	θ_{JA}		100		$^{\circ}\text{C}/\text{W}$	Double-sided PCB in free air		
	0.15" SOIC16			82					
	0.3" SOIC16			67					
Junction–Case (Top) Thermal Resistance	QSOP	θ_{JC}		9			$^{\circ}\text{C}/\text{W}$	2s2p PCB in free air per JESD51	
	0.15" SOIC16			8					
	0.3" SOIC16			12					
Junction–Ambient Thermal Resistance	0.3" SOIC	θ_{JA}		46		$^{\circ}\text{C}/\text{W}$		2s2p PCB in free air per JESD51	
Junction–Case (Top) Thermal Resistance		θ_{JC}		9					
Power Dissipation	QSOP	P_{D}			675				mW
	0.15" SOIC16				675				
	0.3" SOIC16				1500				

Notes:

- Absolute maximum means the device will not be damaged if operated under these conditions. It does not guarantee performance.
- PWD is defined as $t_{\text{PHL}} - t_{\text{PLH}}$. %PWD is equal to PWD divided by pulse width.
- t_{PSK} is the magnitude of the worst-case difference in t_{PHL} and/or t_{PLH} between devices at 25°C.
- CM_{H} is the maximum common mode voltage slew rate that can be sustained while maintaining $V_{\text{O}} > 0.8 V_{\text{DD2}}$. CM_{L} is the maximum common mode input voltage that can be sustained while maintaining $V_{\text{O}} < 0.8 \text{ V}$. The common mode voltage slew rates apply to both rising and falling common mode voltage edges.
- Device is considered a two-terminal device: pins 1–8 shorted and pins 9–16 shorted.
- Dynamic power consumption numbers are calculated per channel and are supplied by the channel's input side power supply.
- Minimum pulse width is the minimum value at which specified PWD is guaranteed.
- The relevant test and measurement methods are given in the Electromagnetic Compatibility section on p. 8.
- External magnetic field immunity is improved by this factor if the field direction is "end-to-end" rather than to "pin-to-pin" (see diagram on p. 8).
- 66,535-bit pseudo-random binary signal (PRBS) NRZ bit pattern with no more than five consecutive 1s or 0s; 800 ps transition time.

Application Information

Electrostatic Discharge Sensitivity

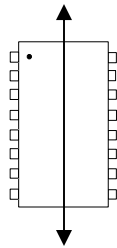
This product has been tested for electrostatic sensitivity to the limits stated in the specifications. However, NVE recommends that all integrated circuits be handled with appropriate care to avoid damage. Damage caused by inappropriate handling or storage could range from performance degradation to complete failure.

Electromagnetic Compatibility

IsoLoop Isolators have the lowest EMC footprint of any isolation technology. There are no internal clocks or carriers. IsoLoop Isolators' Wheatstone bridge configuration and differential magnetic field signaling ensure excellent EMC performance against all relevant standards.

These isolators are fully compliant with IEC 61000-6-1 and IEC 61000-6-2 standards for immunity, and IEC 61000-6-3, IEC 61000-6-4, CISPR, and FCC Class A standards for emissions.

Immunity to external magnetic fields is even higher if the field direction is "end-to-end" rather than to "pin-to-pin" as shown in the diagram below:



Cross-axis Field Direction

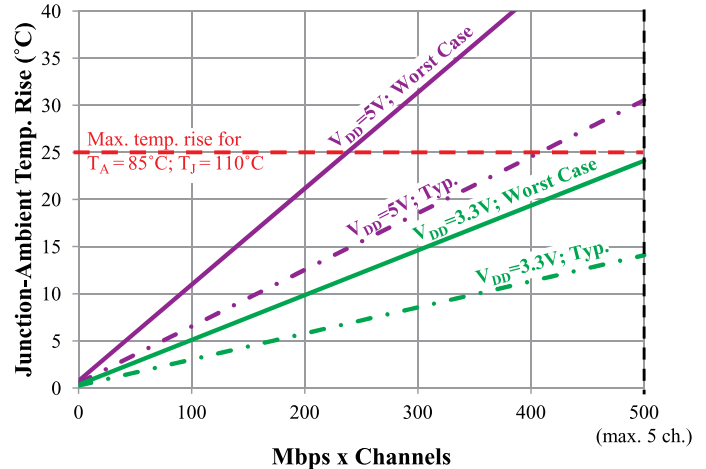
Dynamic Power Consumption

IsoLoop Isolators achieve their low power consumption from the way they transmit data across the isolation barrier. By detecting the edge transitions of the input logic signal and converting these to narrow current pulses, a magnetic field is created around the GMR Wheatstone bridge. Depending on the direction of the magnetic field, the bridge causes the output comparator to switch following the input logic signal. Since the current pulses are narrow, about 2.5 ns, the power consumption is independent of mark-to-space ratio and solely dependent on frequency. This has obvious advantages over optocouplers, which have power consumption heavily dependent on mark-to-space ratio.

Thermal Management

IsoLoop Isolators are designed for low power dissipation and thermal performance, providing unmatched channel density for high-performance isolators. Nevertheless, package temperature rise should be considered when running multiple channels at high speed. Power consumption is higher at 5 volt operation than at 3.3 volts, and dynamic supply current is higher on the input side of the isolators than on the output side, so thermal management is more important with five-volt input-side power supplies.

IL260/IL261/IL262 parts have a maximum junction temperature of 110°C. Based on the specifications contained in this datasheet, the derating curve at typical operating conditions is as follows:



Power Supply Decoupling

Both power supplies should be bypassed with 0.1 μF typical (0.047 μF minimum) capacitors as close as possible to the V_{DD} pins. Ground planes for both GND₁ and GND₂ are highly recommended for data rates above 10 Mbps.

Maintaining Creepage

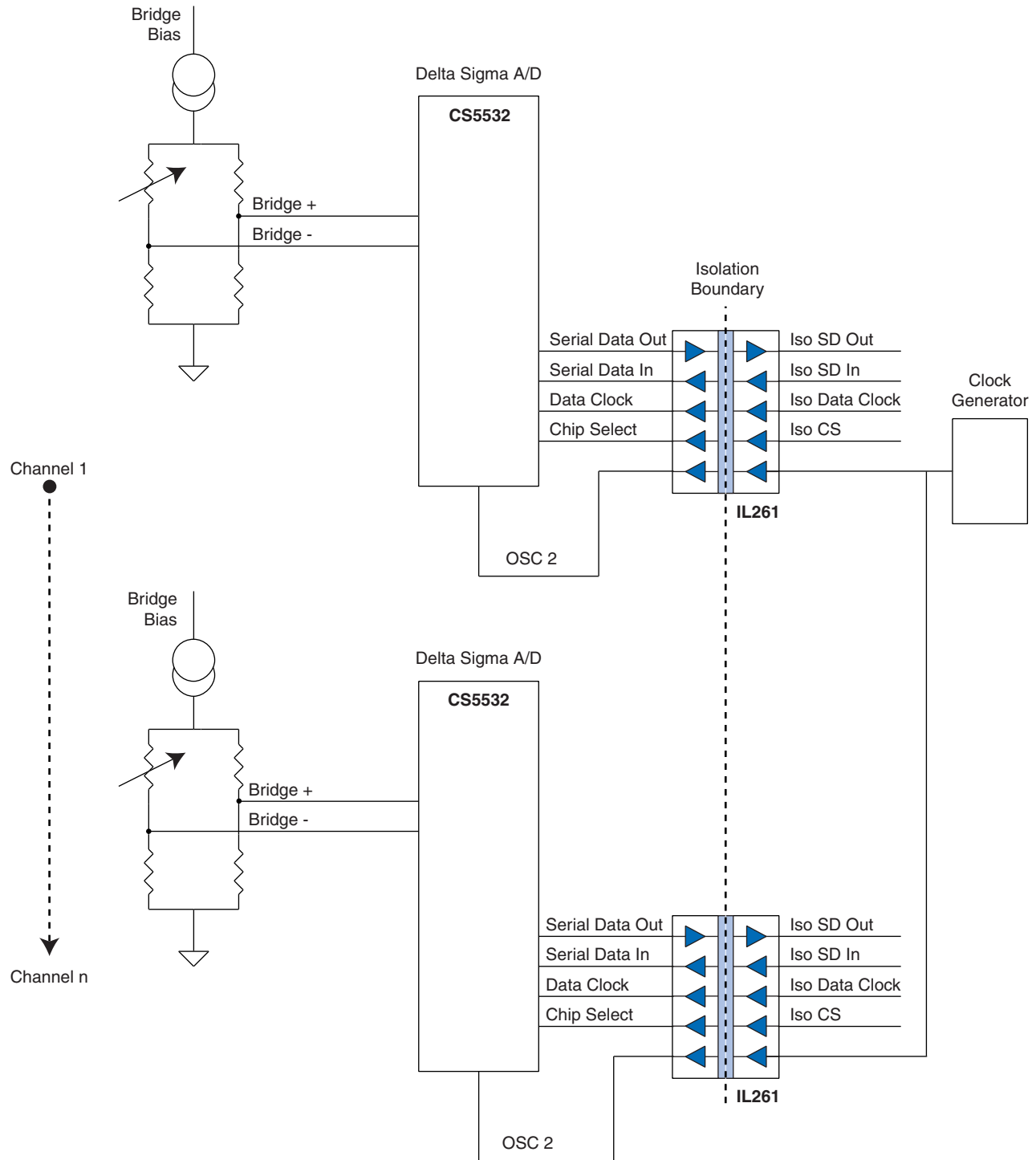
Creepage distances are often critical in isolated circuits. In addition to meeting JEDEC standards, NVE isolator packages have unique creepage specifications. Standard pad libraries often extend under the package, compromising creepage and clearance. Similarly, ground planes, if used, should be spaced to avoid compromising clearance. Package drawings and recommended pad layouts are included in this datasheet.

Signal Status on Start-up and Shut Down

To minimize power dissipation, input signals are differentiated and then latched on the output side of the isolation barrier to reconstruct the signal. This could result in an ambiguous output state depending on power up, shutdown and power loss sequencing. Therefore, the designer should consider including an initialization signal in the start-up circuit. Initialization consists of toggling the input either high then low, or low then high.

Application Diagram—Multi-Channel Delta-Sigma A/D Converter

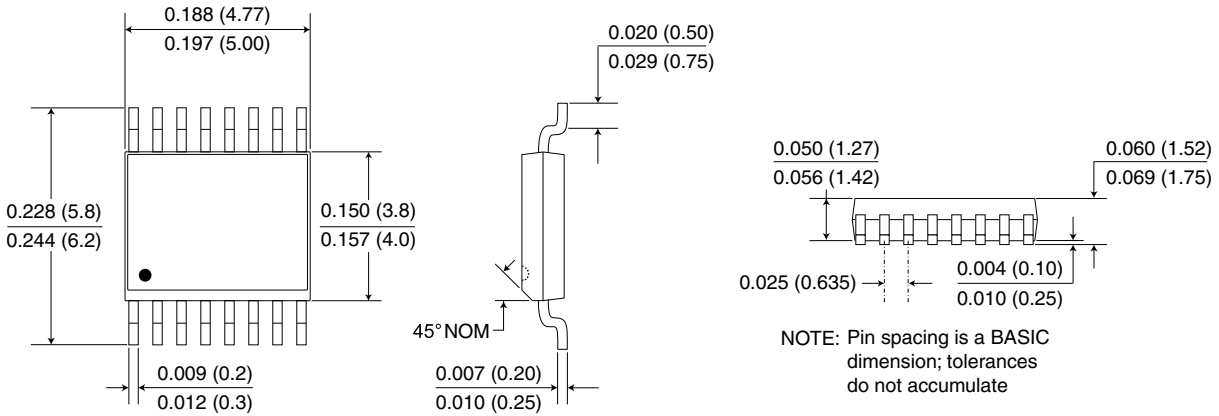
In a typical single-channel delta-sigma ADC, the system clock is located on the isolated side of the system and only four channels of isolation are required. With multiple ADCs configured in a channel-to-channel isolation configuration, however, clock jitter and edge placement accuracy of the system clock must be matched between ADCs. The best solution is to use a single clock on the system side and distribute the clock to each ADC. The five-channel IL261 is ideal, with the fifth channel used to distribute a single, isolated clock to multiple ADCs as shown below:



Package Drawings

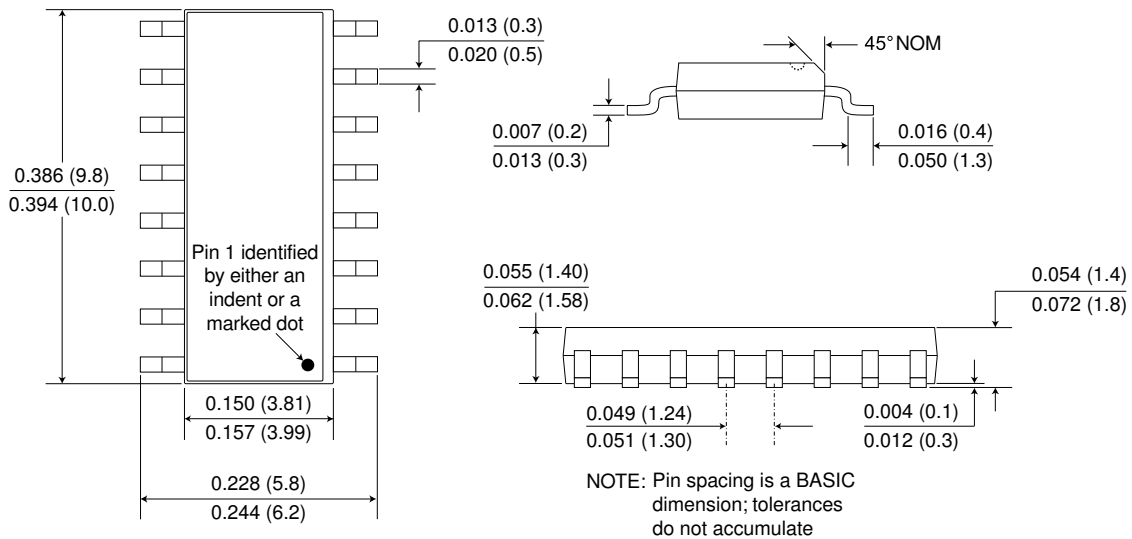
Ultraminiature 16-pin QSOP Package (-1 suffix)

Dimensions in inches (mm); scale = approx. 5X



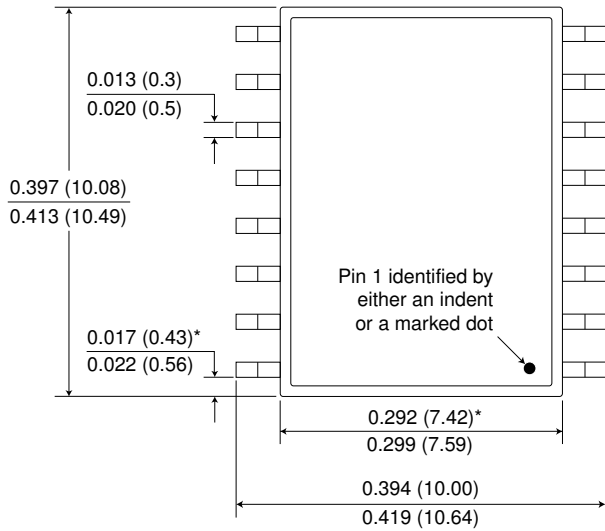
0.15" 16-pin SOIC Package (-3 suffix)

Dimensions in inches (mm); scale = approx. 5X



0.3" 16-pin SOIC Package (no suffix)

Dimensions in inches (mm); scale = approx. 5X



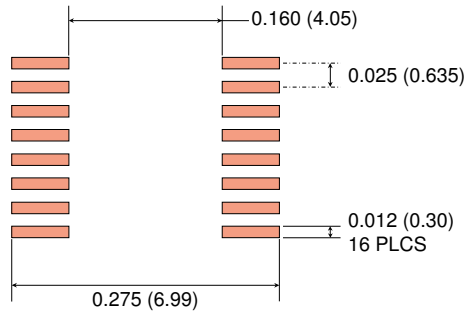
NOTE: Pin spacing is a BASIC dimension; tolerances do not accumulate

*Specified for True 8™ package to guarantee 8 mm creepage per IEC 60601.

Recommended Pad Layouts

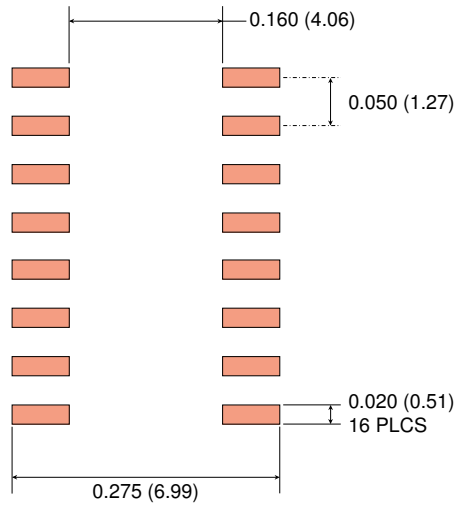
4 mm x 5 mm 16-pin QSOP Pad Layout

Dimensions in inches (mm); scale = approx. 5X



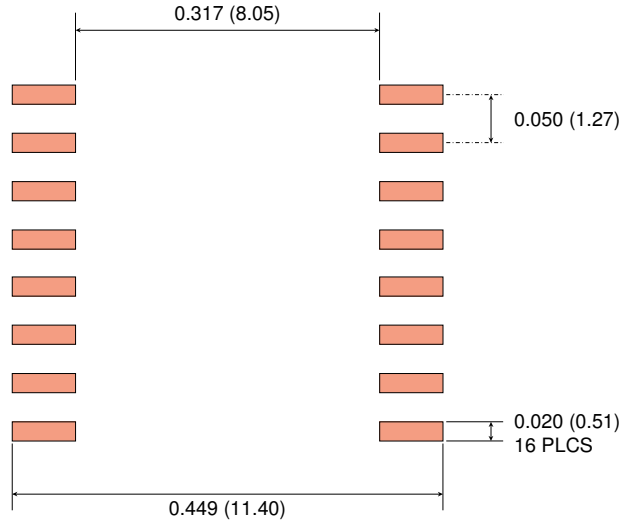
0.15" 16-pin SOIC Pad Layout

Dimensions in inches (mm); scale = approx. 5X



0.3" 16-pin SOIC Pad Layout

Dimensions in inches (mm); scale = approx. 5X





IL260/IL261/IL262

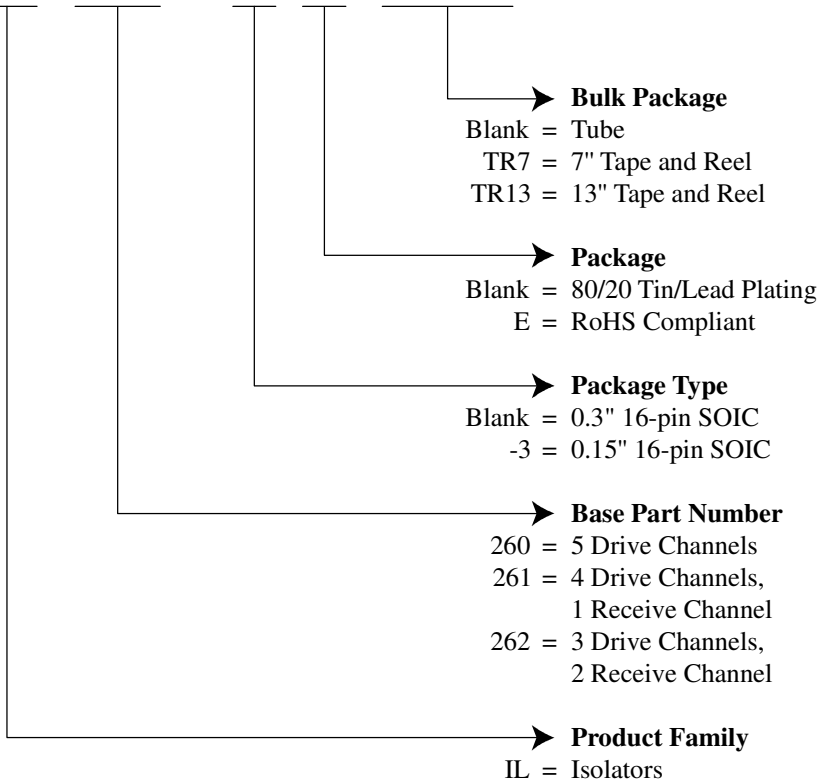
Available Parts

Available Parts	Transmit Channels	Receive Channels	Isolation Voltage (RMS)	Package
IL260-1E	5	0	2.5 kV	QSOP
IL260-3E	5	0	2.5 kV	Narrow SOIC
IL260E	5	0	2.5 kV	Wide SOIC
IL260VE	5	0	6 kV	Wide SOIC
IL261-1E	4	1	2.5 kV	QSOP
IL261-3E	4	1	2.5 kV	Narrow SOIC
IL261E	4	1	2.5 kV	Wide SOIC
IL261VE	4	1	6 kV	Wide SOIC
IL262-3E	3	2	2.5 kV	Narrow SOIC
IL262E	3	2	2.5 kV	Wide SOIC
IL262VE	3	2	6 kV	Wide SOIC

All part types are available on tape and reel.

Part Numbering

IL 260 - 3 E TR13



Revision History

ISB-DS-001-IL260/1/2-Y February 2023

Changes

- Increased minimum supply voltage from 2.5 V to 2.7 V (p. 2).
- Eliminated redundant “valid part numbers” list (p. 14).

ISB-DS-001-IL260/1/2-X

Changes

- Upgraded to IEC 60747-17 (VDE 0884-17):2021-10 (p. 3).
- Increased Working Voltage ratings based on latest VDE testing (p. 3).

ISB-DS-001-IL260/1/2-W

Changes

- Reduced minimum supply voltage to 2.5 V (p. 2).
- Updated EMC standards.
- Deleted minimum magnetic field immunity specifications (not 100% tested).
- Updated thermal specifications (p. 7).

ISB-DS-001-IL260/1/2-V

Change

- VDE certification and UL approval for V-Series versions (6 kV reinforced isolation).

ISB-DS-001-IL260/1/2-U

Changes

- Updated VDE certification standard to VDE V 0884-10.
- Upgraded “VE” Version Surge Immunity specification to 12.8 kV.
- Upgraded “VE” Version VDE 0884-10 rating to reinforced insulation.
- Corrected QSOP pin width dimension (p. 10).

ISB-DS-001-IL260/1/2-T

Changes

- Increased V-Series isolation voltage to 6 kVrms.
- Increased typ. Total Barrier Thickness specification to 0.016 mm.
- Increased CTI min. specification to $\geq 600 V_{RMS}$.

ISB-DS-001-IL260/1/2-S

Changes

- Added V-Series 5 kV isolation voltage versions.
- More detailed “Available Parts” table.

ISB-DS-001-IL260/1/2-R

Changes

- Added QSOP packages (-1 suffix).
- Revised and added details to thermal characteristic specifications (p. 2).
- Added VDE 0884 Safety-Limiting Values (p. 3).
- Added “Thermal Management” paragraph in Applications section.



IL260/IL261/IL262

Datasheet Limitations

The information and data provided in datasheets shall define the specification of the product as agreed between NVE and its customer, unless NVE and customer have explicitly agreed otherwise in writing. All specifications are based on NVE test protocols. In no event however, shall an agreement be valid in which the NVE product is deemed to offer functions and qualities beyond those described in the datasheet.

Limited Warranty and Liability

Information in this document is believed to be accurate and reliable. However, NVE does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall NVE be liable for any indirect, incidental, punitive, special or consequential damages (including, without limitation, lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Right to Make Changes

NVE reserves the right to make changes to information published in this document including, without limitation, specifications and product descriptions at any time and without notice. This document supersedes and replaces all information supplied prior to its publication.

Use in Life-Critical or Safety-Critical Applications

Unless NVE and a customer explicitly agree otherwise in writing, NVE products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical devices or equipment. NVE accepts no liability for inclusion or use of NVE products in such applications and such inclusion or use is at the customer's own risk. Should the customer use NVE products for such application whether authorized by NVE or not, the customer shall indemnify and hold NVE harmless against all claims and damages.

Applications

Applications described in this datasheet are illustrative only. NVE makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NVE products, and NVE accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NVE product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customers. Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NVE does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customers. The customer is responsible for all necessary testing for the customer's applications and products using NVE products in order to avoid a default of the applications and the products or of the application or use by customer's third party customers. NVE accepts no liability in this respect.

Limiting Values

Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the recommended operating conditions of the datasheet is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and Conditions of Sale

In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NVE hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NVE products by customer.

No Offer to Sell or License

Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export Control

This document as well as the items described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

Automotive Qualified Products

Unless the datasheet expressly states that a specific NVE product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NVE accepts no liability for inclusion or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NVE's warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NVE's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NVE for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NVE's standard warranty and NVE's product specifications.

An ISO 9001 Certified Company

NVE Corporation
11409 Valley View Road
Eden Prairie, MN 55344-3617 USA
Telephone: (952) 829-9217

www.nve.com
e-mail: iso-info@nve.com

©NVE Corporation
All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

ISB-DS-001-IL260/1/2-Y

February 2023

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we stricly control the quality of products and services. Welcome your RFQ to

Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.